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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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GA080TH65

Silicon Carbide Thyristor

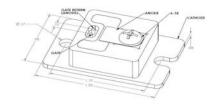
V _{FBM}	=	6500 V	
I _{T(AVM)}	=	80 A	
Q _{rr}	=	4.2 μC	

Features

- 6500 V Asymmetric SiC NPNP Thyristor
- 150 °C operating temperature
- Robust compact fully soldered package
- SOT-227 (ISOTOP) base plate form factor
- Fast turn on characteristics
- Lowest in class Q_{rr}/I_{T(AVM)}

Applications

- Grid Tied Solar Inverters
- Wind Power Inverters
- HVDC Power Conversion
- Utility Scale Power Conversion
- Trigger Circuits/Ignition Circuits



Package



Maximum Ratings

Parameter	Symbol	Conditions	Values	Unit
Repetitive peak forward voltage	V_{FBM}	T _j = 25 °C	6500	V
Repetitive peak reverse voltage	V_{RBM}	T _j = 25 °C	50	V
Maximum average on-state current	I _{T(AVM)}	T _c ≤ 125 °C	80	Α
RMS on-state current	I _{T(RMS)}	T _c ≤ 125 °C	139	Α
Non-repetitive peak on-state current	I _{T.max}	$T_{\rm C}$ = 25 °C, $t_{\rm p}$ = 2 us, D = 0.1	tbd	Α
Power dissipation	P _{tot}	T _C = 25 °C	1563	W
Operating and storage temperature	T _i , T _{sta}		-55 to 150	°C

Electrical Characteristics

Parameter	Cumbal	Conditions	Values		l lmis	
	Symbol		min.	typ.	max.	Unit
Maximum peak on state voltage	V	I _K = -80 A, T _j = 25 °C		-3.70		V
	$V_{KA(ON)}$	I _K = -80 A, T _i = 150 °C		-3.45		
Anode-cathode threshold voltage	$V_{KA(TO)}$	T _j = 25 °C (150 °C)		-3.0(-2.7)		V
Anode-cathode slope resistance	R _{AK}	T _j = 25 °C (150 °C), I _K = -80 A		6.0(6.3)		mΩ
Lackage surrent	ı	V _{KA} = -6500 V, V _{GA} = 0 V, T _i = 25 °C		15		μA
Leakage current	ı _L	$V_{KA} = -6500 \text{ V}, V_{GA} = 0 \text{ V}, T_{j} = 150 ^{\circ}\text{C}$		50		
Gate trigger current	I _{GT}	$T_{_{\rm J}}$ = 25 °C, $t_{_{\rm P}}$ = 10 μ s		-100		mA
Holding current	I _H	T _j = 25 °C		tbd		mA
Rise time	t _R	I _G = -3 A, V _{KA} = -2200 V		190		ns
Delay time	t _D	$I_{K} = -80 \text{ A}, T_{j} = 25 ^{\circ}\text{C}$		50		ns
Reverse recovery charge	Q _{rr}			4.2		μC
Recovered charge, 50% chord	Q_{ra}	$dI/dt = 430 \text{ A/us}, I_{K} = -70 \text{ A}, V_{KA} = 20 \text{ V}$		2.3		μC
Reverse recovery current	I _m	$dV/dt(re-app) = -460 V/us, T_i = 25 °C$		20		Α
Circuit commutated turn-off time	tq	,		10.1		μs

Thermal Characteristics

Thermal resistance, junction - case	R_{thJC}		0.08	°C/W
Mechanical Properties				
Mounting torque for base	M _b	Heat sink surface must be optically flat	1.5	Nm
Mounting torque for top	M,		1.3	Nm

W,

Weight

30

^{1.} Considering worst case Z_{th} conditions



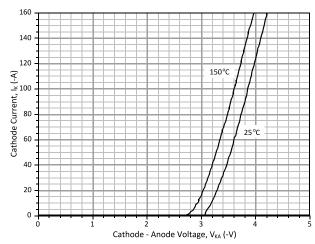


Figure 1: Typical On State Characteristics

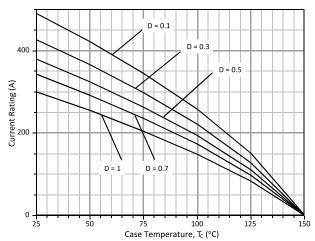


Figure 3: Typical Current Derating Curves (D = t_p/T , t_p = 400 μs^1)

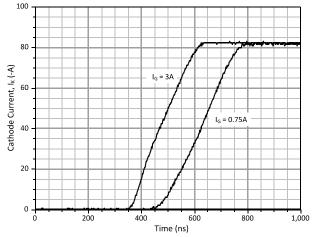


Figure 5: Typical Turn On Characteristics at 25 °C

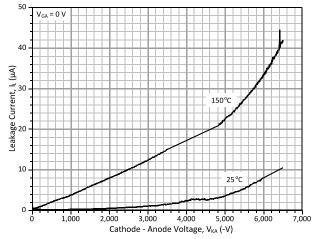


Figure 2: Typical Forward Blocking Characteristics

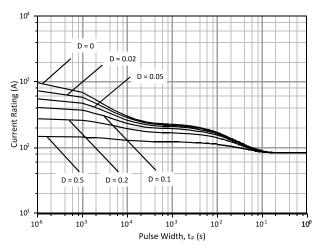


Figure 4: Typical Current Rating versus Pulse Duration Curves at $T_{\rm c}$ = 120 $^{\rm o}$ C

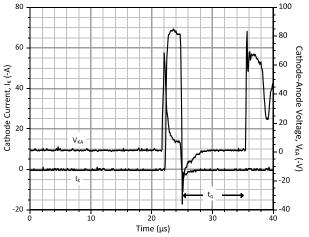
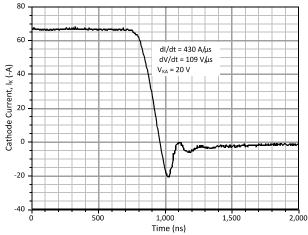


Figure 6: Typical Turn Off Characteristics at 25 °C





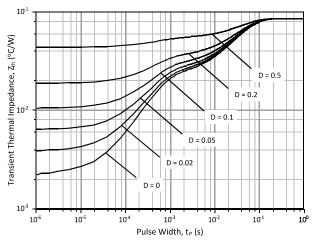


Figure 8: Typical Transient Thermal Impedance

Revision History				
Date	Revision	Comments	Supersedes	
2010/11/13	1	First generation release		

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